

SID

Factory: Rot am See

Article:

728

ML4

Provided:

Kracht, Enrico

Customer:

Date:

27.02.2017



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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Polyimid 50µ -18µ eins CU Kleberlos 460x305...	50201120	<div>18</div> <div>50</div>	VS	<div>1</div> <div></div>	B00
A-RS-FR4-Prepreg-106-LowFlow-R1551LE	50200912	<div>50</div>		<div>2</div> <div></div>	
A-RS-FR4-ML-0.71mm-018+018-TG150-HF	50200793	<div>0</div> <div>710</div> <div>0</div>	L2	<div>3</div> <div></div>	
A-RS-FR4-Prepreg-106-TG150-HF	50200640	<div>50</div>	L3	<div>4</div> <div></div>	
A-RS Kupferfolie-018my 330x490mm	50200238	<div>18</div>	RS	<div>5</div> <div></div>	

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

896 µm

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